

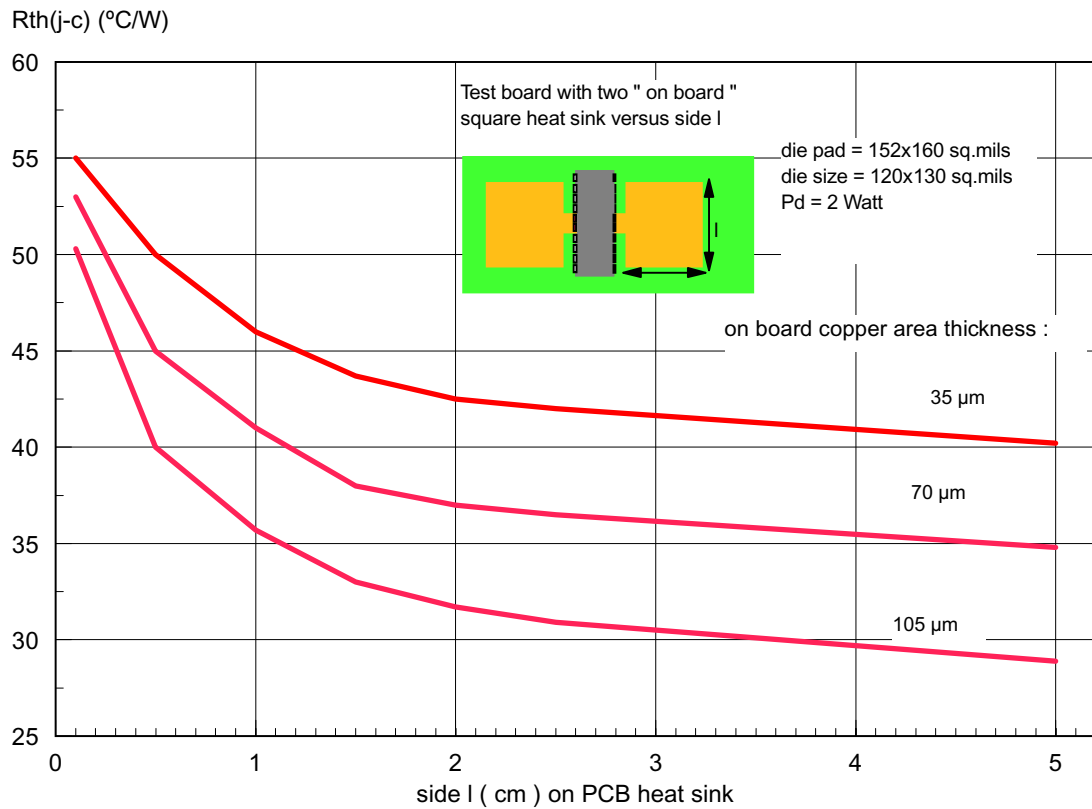
### PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.6 W/cm°C
die attach	epoxy glue (silver filled)	15-50 $\mu$ m	0.01 W/cm°C
molding compound	epoxy resin	3 mm	0.0063W/cm°C

Charts enclosed :

- 1)  $R_{th}(j-a)$  vs on board heat sink
- 2)  $Z_{th}(j-a)$  vs time width

1)



2)

